Welcome to the World of Standards



World Class Standards

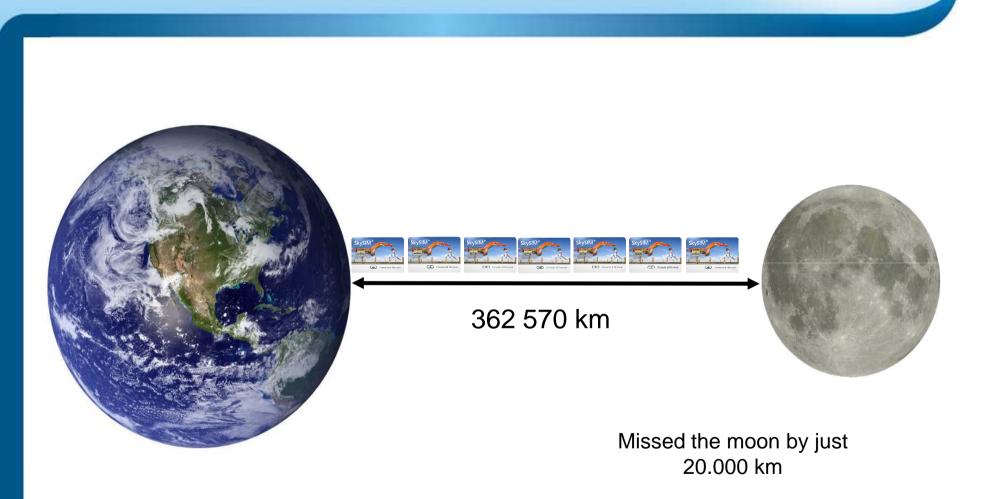
Dr. Klaus Vedder Chairman ETSI TC SCP

The UICC Recent Work of ETSI TC Smart Card Platform

7th ETSI Security Workshop, Sophia Antipolis, France, 18-19 January 2012

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SIMs, USIMs, R-UIMs, CSIMs.... in 2011



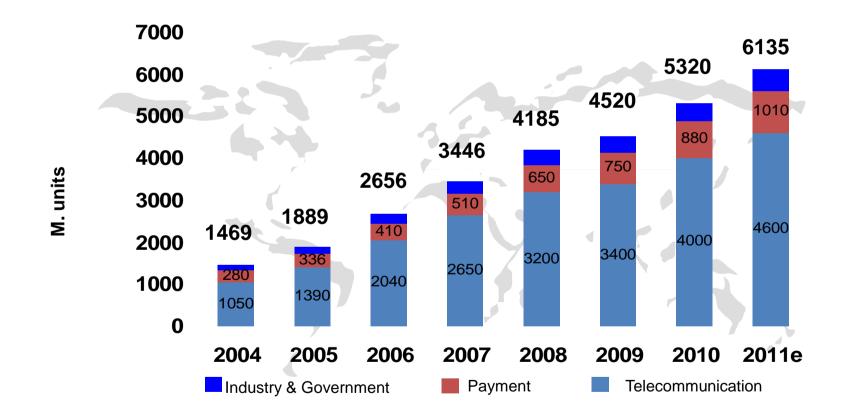
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The Smart Card Market





Source: Eurosmart



ETSI TC Smart Card Platform



- 24 Years of Dedication and Real-life Experience
 - TC SCP was founded in March 2000 as the successor of SMG9, the people who specified the most successful smart card application ever with well over 5 billion subscribers using one or more of the over 25 billion SIMs, USIMs, R-UIMs, CSIMs, ... delivered to the market
- ETSI TC SCP has published over fifty specifications on smart cards encompassing for every topic the whole range from requirements via the technical solution to the test specification; topics range from administrative commands to APIs, browsers, Internet connectivity, Machine-to-Machine, new interfaces for high speed and NFC as well as remote management
 - All can be downloaded free of charge from the ETSI website

The specifications are application agnostic and are not restricted to the world of telecommunications. They can be used as a (secure) platform for basically any application.



Structure and Officials



SCP Plenary

Chairman: Klaus Vedder, G&D Vice Chairman: Tim Evans, Illuminismo Vice Chairman: Heiko Kruse, Morpho

SCP Requirement WG

Chairman: Colin Hamling, Telefónica

Vice Chairman: Heiko Kruse, Morpho Vice Chairman: Denis Praca, Gemalto

SCP Technical WG

Chairman: Paul Jolivet, LG Vice Chairman: Sebastian Hans, Oracle

SCP Testing WG

Chairman: Andreas Bertling, Comprion

Vice Chairman: Christophe Dubois, Gemalto



Description

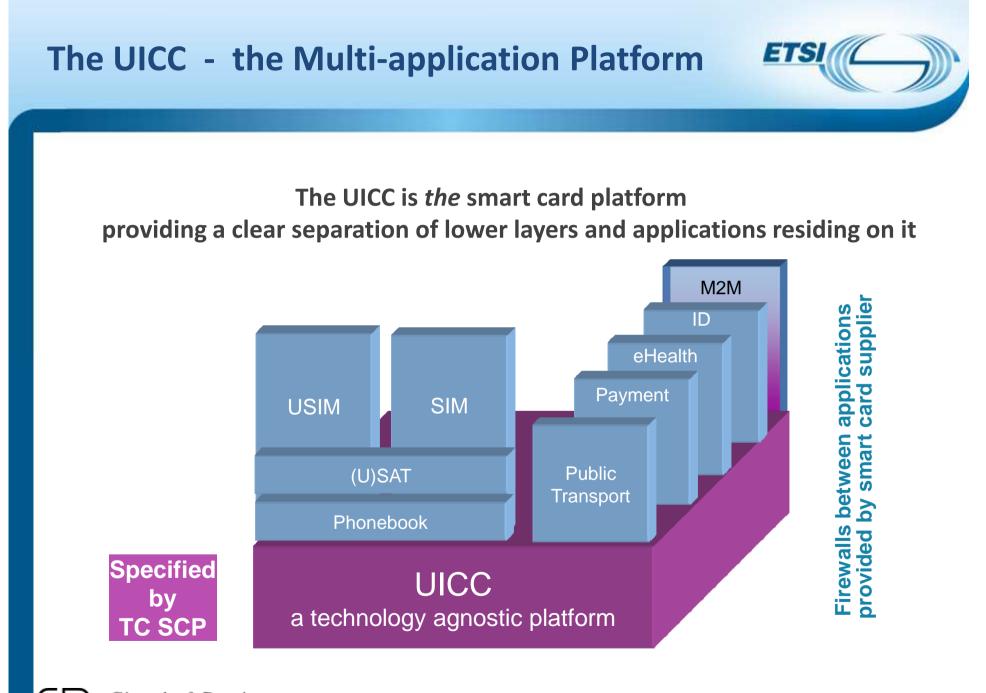
SCP

- Final acceptance of Work Items to be progressed by Working Groups
- Acceptance for publication of all Technical Specifications and Technical Reports as well as Change Requests to published documents

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- Input to its work is received from ETSI members as well as 3GPP, 3GPP2, GlobalPlatform, GSMA, GSMA SCaG, Global Certification Forum (GCF), NFC Forum, OMA, ...
- SCP REQ
 - Working Group SCP REQ is responsible for developing the requirements for the Smart Card Platform
- SCP TEC
 - Working Group SCP TEC is responsible for the technical realisation of the requirements developed by SCP REQ and accepted by SCP
- SCP TEST
 - Working Group SCP TEST is responsible for the development of test specifications for deliverables produced by SCP TEC and accepted by SCP





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A year of consolidation, after completion of eight specifications in 2010, with two exciting new topics.

The 4th Form Factor

- Collection of use cases and requirements for a UICC form factor smaller by 25% to 40% than the one known as Mini-UICC or 3FF. While smaller, this form factor would retain the existing UICC functionalities
- Development of the technical specifications for a fourth UICC form factor (4FF) in accordance with the technical requirements and selection criteria

The embedded UICC

• A new approach for the M2M environment, revolutionizing the life of the SIM



2011 in a Nutshell



- Card Application Toolkit can now be executed on composite devices (e.g., M2M module with an external display)
- Two customer organizations of TC SCP use the Secure Channel for the specification of their features
 - 3GPP for secure communications between the USIM application and a Relay Node; OMA for use in the OMA BCAST specifications

Work on a related test specification started

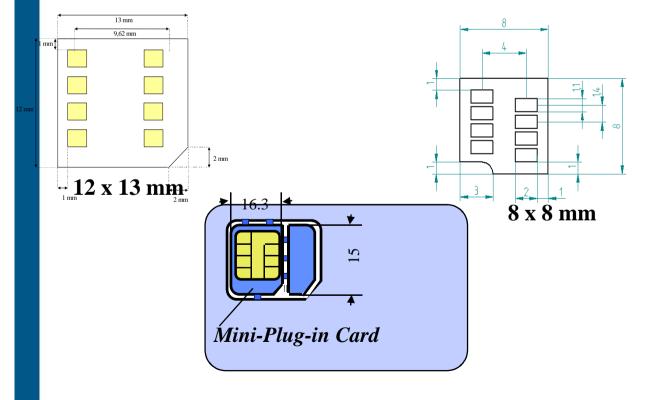
- SCP started the following new Work Items
 - Requirements for an embedded UICC
 - Memory integrity monitoring in M2M applications
 - Test Specification of the architecture, functional capabilities and characteristics of the Secure Channel
 - Test Specification for UICC Application Programming Interface for Java Card[™] for Contactless Applications
 - Requirements and technical solution for a 4th Form Factor
 - P2P mode for contactless communications
 - Giesecke & Devrient

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2003: How Small is Small ?



- May enable use of devices currently not feasible for Plug-in cards
- Backwards compatibility necessary (?)
- Also traded under the name micro-SIM





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The standardised mini-UICC as part of the Plug-in card being part of the ID-1 card

3FF: A hardware "SIM-lock"?

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Motivation for Yet Another Form Factor				
 Nearly 8 years after the standardisation of the 3rd Form Factor (or mini-UICC, "micro SIM") Apple introduced this as a "first" mover into its devices Plug-in: 15x25 mm 3FF: 12x15 mm 				
Large device manufacturers are now adopting the 3FF				
BUT				
Today's SIM card and connector are the most expensive piece of real estate on a PCB				

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A New Work Item for a Smaller SIM Card

- "4FF" the 4th Form Factor
 - Smaller and thinner (than 3FF) removable SIM card
- Backwards compatibility
 - The new form factor should support existing functionality
- Adapter readiness
 - Thinner to allow adapters so that the 4FF can be "clicked" into adapters for use as a Plug-in SIM or 3FF SIM giving a kind of backward usability
- Supported by all BIG MNO Groups
 - AT&T, Deutsche Telekom AG, France Telecom/Orange SA, Telefonica SA, Verizon Wireless, Vodafone Group

ETSI TC SCP # Marseille, Fran	ce, 16 – 17 June 2011		SCP(11)0254r1	
New W	ork Item Form	Form to be used when prop adoption onto th	oosing new Work Items fo e ETSI Work Programmi	
ATTENTION: Befor latest Word version	e starting towork on a revision of a pu In case of multi-part deliverable, p. Work	ublished ETSI document, contact edi lease use ONE work item form for Item details	thelp@etsi.org to obtain th EACH part	
Which Technical Body is responsible? ETSI TC Smart Card Platform (TC SCP)		Sub Group: SCP REQ Project:		
WI reference number (if known):		Will an STF be requested? [Yes / No] STF number (if known):		
(number will be allocated by Secretariat if not shown)		EC mandate number (if relevant): BC		
Formal title of deliverable	Use Cases and Requirements	related to Fourth UICC Form Factor		
Working title: Fourth UICC Form Factor (4FF)	Scope of work to be under The scope of this work item is o			
	a new form factor which is easi it is expected that SCP REQ sh • That the proposed siz 40%) than the current allowing easy handling	12 to defail the use cases, requirem ly removable and replaceable by the sall consider the following key points e of the new form factor shall be muc Min-UPC to achieve a size optimiz g of the UPC by end user (i.e. withou actionalities as defined in ETSI speci	end user. in this work item: h smaller (at least 25%- tition of terminals while at requiring specific tools)	
Rapporteur (named	ndividual person):	Supporting ETSI Member organisat	ions:	
name: Nausi	nad Zaveri	(name at least four) 1. Apple	5 Telefonica SA	
organisation: _Apple too e-mail: Nzaveri@apple.com		2. AT&T	6. Verizon Wireless 7. Vodatone Group	
	Deliverable	a document details:		
What type of docum	ent will be produced?	Is it a new document or a revi	sion of an existing one?	
EN[_] EG[_] ES[_] TS[X] TR[_] SR[_] GS [_] For EN deliverables only: - Is the draft EN to be approved by One-step Approval or Two-step Approval Procedure? [OAP / TAP] - Candidate harmonized standard? [OAP / TAP] - - Directive: - [OAP / TAP]		[revision] If a revision, state the deliverable (e.g. TS 102 997 v1.1.1) being revised: _TS 102 412edition /version		
Hierarchy: if this in reference of its paren	Work tem fits in a hierarchical tree (see <u>10</u> t node (WI reference / deliverable number	P clause 1.6.1), its position shall then be / topic name).	indicated here by giving the	
	Wo	rk schedule;		
	Milestone name • TB adoption of WI	Target date	-	
	Early Draft	SCP REQ #32		
	Stable Draft	SCP REQ #33		
		SCP RED #33		
	Draft for approval			
	 W/G approval (serie in vito) 	SCP RED # 33 SCP # 52		
		SCP RED # 33		
Remarks:	WG approval detels the Villo TB approval	SCP REQ # 33 SCP # 52		
	WG approval (etck trns viii) T8 approval T6 approval To be published as version:	SCP REQ # 33 SCP # 52	PCIS IYes / No1	
Remarks:	WG approval (etck trns viii) T8 approval T6 approval To be published as version:	SCP # 53 SCP # 52 V	e <u>CS</u> [Yes / No]	

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Some Early Thoughts

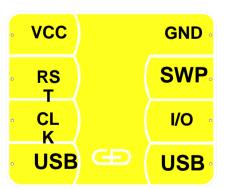
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No plastic around the contact plate

- Cutting away <u>all</u> "excessive" plastic around an 8 contact 3FF SIM card would give a saving in area of ~30% over the 3FF SIM - new size: 10.4x 12.2 mm
- However, a small rim of isolating material is <u>absolutely</u> necessary to avoid short circuits with the socket (problems with hand-made 3FFs)

If we want to be really small

- What about contacts C4 and C8 which are used for the USB interface ?
 - ~70% of today's SIMs are delivered with a 6 pin contact plate
- How do we cater for the USB interface ?
 - Additional contact(s) in the middle of the contact plate
 - Switch of protocol from T=0 to USB during operation using the other existing contacts
 - Replace T=0 interface by USB interface and give up backwards compatibility
 - not a solution any longer





Savings by Cutting Away Plastic



	Height	Width	Area	Saving wrt Plug-in
Card	•			
Plug-in (1989)	15	25	375	
3FF (2004)	12	15	180	52%
6 pin 4FF	9*	12*	108	71% (40% wrt 3FF)
8 pin 4FF "w/o plastic"	10.4*	12.2*	127	66% (30% wrt 3FF)
* rough figures				
In comparison: MFF2	5	6	30	

The 10 Requirements (Agreed)

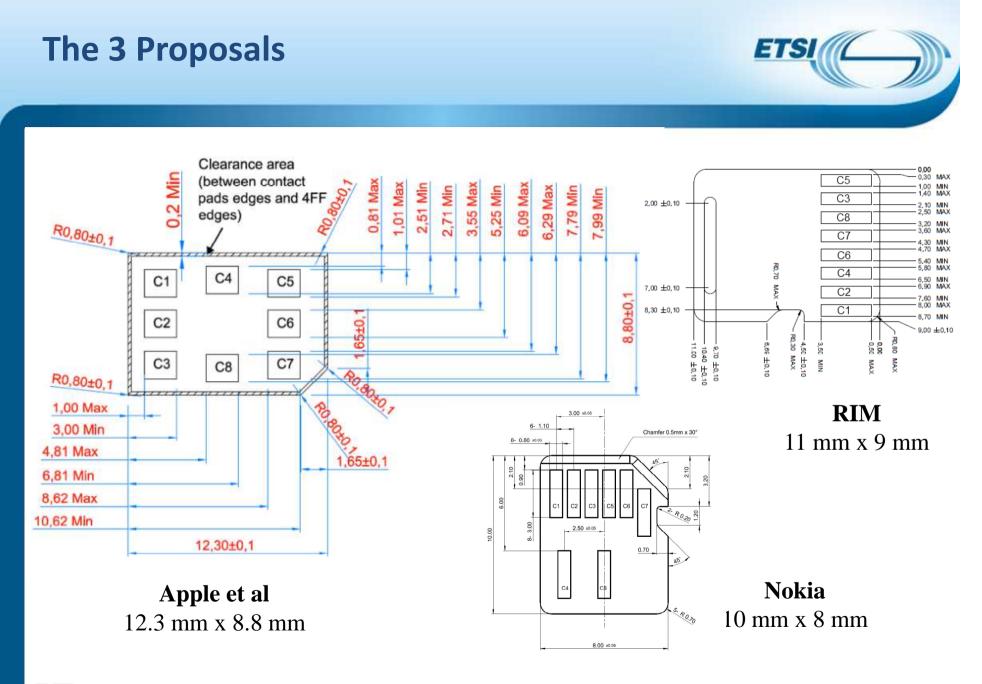


- The fourth UICC form factor shall be at least 25% smaller as compared to the Mini-UICC.
- **Ohereon and a set of the set of**
- **Solution** The fourth UICC form factor shall specify 8 contacts.
- The usage of the 8 contacts of the fourth UICC form factor shall be compliant with ETSI TS 102 221 Section 4.5.
- The fourth UICC form factor shall retain all existing UICC functionalities as specified in the existing ETSI specifications.
- It shall be possible to have a legible identifier (e.g. at least ICCID) on a UICC complying to the fourth UICC form factor.
- The fourth UICC form factor shall be easily removable and replaceable by the end user (i.e. without requiring specific tools).
- The design of the fourth UICC form factor shall prevent the 4FF from becoming jammed in a Mini-UICC reader. An example is that if the 4FF is turned 90 degrees and it fits perfectly into the Mini-UICC reader (4FF length = Mini-UICC width).
- The need for an orientation mark to prevent wrong insertion (4FF into 4FF reader) should be considered in order to prevent "electrical damage" of the UICC.
- There shall be a maximum contact pad size defined in order to prevent the contact pad metal to stretch to the 4FF card edge (e.g. min. 0.2 mm clearance towards the edge).



The 4 Selection Criteria (Agreed)

- ETSI
- The following selection criteria is to be used when selecting a technical solution in case several technical solutions meet the requirements specified in the present document.
 - A preference is to be given to a technical solution for the 4FF that provides an overall space saving, including the mechanical reader, compared to a solution where the UICC size reduction is higher but the size reduction including the mechanical reader is less.
 - In case of several solutions providing similar size reduction a preference is to be given to a solution based on the existing plug-in/mini UICC contact layout (size and arrangement) compared to a solution based on a different contact layout.
 - In case of several solutions providing similar size reduction a preference is to be given to a solution with a shorter time to market than a solution with a longer time to market. Time to market includes availability of both UICCs and mechanical readers.
 - A technical solution that prevents "electrical damage" in case of wrong insertion is to be given a preference compared to a solution not providing such protection.



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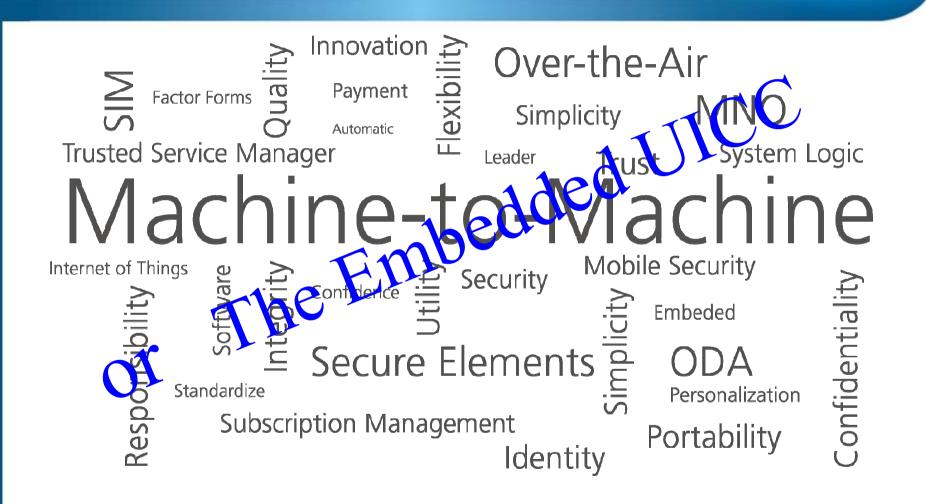
The One Solution





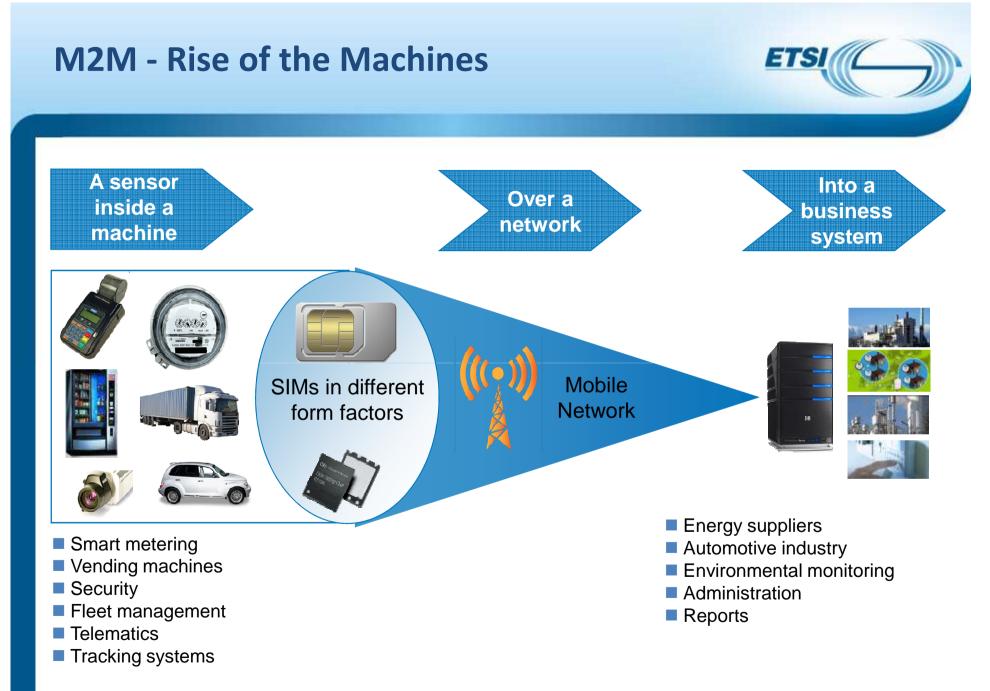
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ETS **Some First Thoughts on M2M** Mobile networks are starting to be used to connect all sorts of devices Wireless for mobility, ease of connection and remote management SIMs may be embedded in devices at manufacture This may even be in advance of choice of country of use and network operator Network operator may be changed during life time of the device The traditional, removable SIM may not be appropriate



for certain applications

The M2M SIM

March 2010: A new specification for UICCs (SIMs) in M2M

- M2M specific constraints such as data retention, temperature, memory update cycles, vibration resistance, humidity
- MFF1 (M2M Form Factor 1) <u>socketable</u> 8 pin solution
- MFF2 : a non-removable, to-be-soldered housing (SON8)



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What is M2M?



Impacts of a Solderable (Not Accessible) M2M UICC (SIM) ETSI

No more "plastic roaming" for the user

• Regulatory issues – need to change the operator

Ownership of an embedded SIM

- In some countries the end user will own the "black beetle"
- No point in stealing a mobile device with an embedded SIM
- Field of usage warranty of M2M SIM supplier
- Future role of the MNOs and service providers (car manufacturers, energy suppliers, ...)
- Lifetime issues of the chip (new SCP Work Item)
- Lifecycle management personalisation and repersonalisation (OTA, OTI, ...) and distribution



A Brief Overview of Events



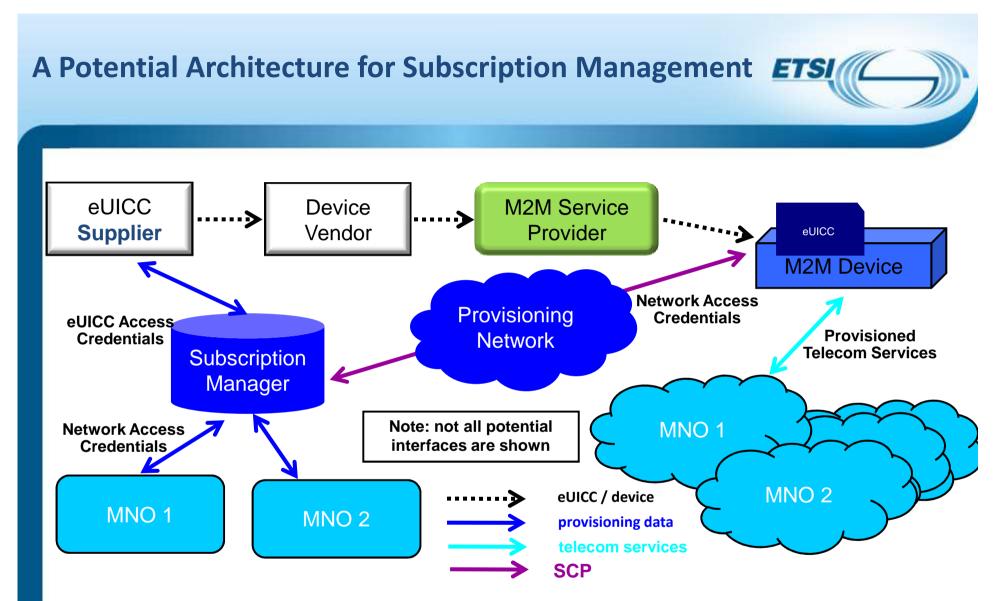
- Following some rumours about embedded SIMs in devices of some company, the GSM Association formed a Task Force on "embedded SIM" in November 2010
- GSMA document "Embedded SIM Task Force Requirements and Use Cases" together with a Work Item proposal given to ETSI SCP in late February 2011
 - GSMA Requirement Document encompasses large parts of a paper by Deutsche Telekom, Telefónica O2 UK, Vodafone Group and G&D
- ETSI work item on use cases and requirements agreed by ETSI SCP in early March 2011
 - Work on Machine-to-Machine (M2M) applications has given rise to the possibility of having a UICC that is embedded in a communication device in such a way that the UICC is not easily accessible or replaceable. The ability to change network subscriptions on such devices becomes problematic, thus necessitating new methods for securely and remotely provisioning access credentials on these Embedded UICCs (eUICC) and managing subscription changes from one operator to another



General Embedded SIM Task Force M2M Use Cases ETSI

No.	Use Case	Description		
UC1	Provisioning of multiple M2M subscriptions.	A Machine-to-Machine Service Provider (M2M SP) sets- up M2M subscriptions for a number of connected M2M devices to start telecommunication services with a first MNO. Optionally, the M2M SP may later change subscriptions to a subsequent MNO.		
UC2	Provision of first subscription with a new connected device	A subscriber purchases a new type of communications or connected device from a device vendor together with a subscription to provide first services to this device.		
UC3	Subscription Change	A subscriber changes the subscription for a device to stop services with the current MNO and start services with a new MNO in accordance with policy control functions for each MNO.		
UC4	Stop Subscription	A subscriber sells his device and stops the subscription for services from the current MNO.		
UC5	Transfer Subscription	Subscriber transfers subscription between devices.		

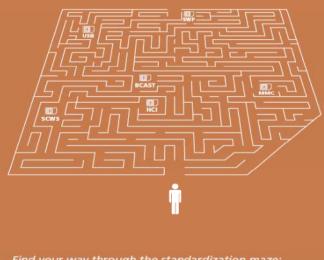




The diagram depicts roles and not entities. The architecture is still under discussion in SCP and, for instance, the role of the Subscription Manager may be split into two, one which prepares the data and one which downloads the data to the UICC







Find your way through the standardization maze: Collect the technologies you need to take mobile telecommunications to the next level.

Next SCP Plenary Meeting 29-30 March in Cupertino see: www.etsi.org

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New Work Items in 2011 (I)

ETSI

Requirements for an Embedded UICC

Reasoning in the Work Item

- Work on Machine-to-Machine (M2M) applications has given rise to the possibility of having a UICC that is embedded in a communication device in such a way that the UICC is not easily accessible or replaceable. The ability to change network subscriptions on such devices becomes problematic, thus necessitating new methods for securely and remotely provisioning access credentials on these Embedded UICCs (eUICC) and managing subscription changes from one operator to another
- This Work Item proposes to identify, analyse and define a representative set of use cases that will provide the key requirements for the development of a trusted framework for the management of an eUICC and for remote personalization and subscription management of such an eUICC including its integration in telecommunication network infrastructures
- It is expected that the use cases will identify aspects that need to be standardised by other organisations such as 3GPP, 3GPP2 and GlobalPlatform





Test Specification for the architecture, functional capabilities and characteristics of the Secure Channel

- This WI will provide a new conformance test specification verifying requirements specified in TS 102 484 *Secure Channel between a UICC and an end-point terminal*. This includes the architecture, functional capabilities and characteristics of the Secure Channel protocol and its associated interfaces transported over the UICC interfaces
- An STF has been formed to develop this specification

Memory integrity monitoring in M2M applications

• Applications running on an M2M UICC may need to face the degradation of non-volatile memory that usually has a limited write cycle guarantee. This work item will deliver optional extensions to the UICC API for Java Card . These extensions allow applications to be alerted if hardware performance is degrading due to its aging and support applications in reducing stress on non-volatile memory for specific data areas



New Work Items in 2011 (III)



- Set Specification for UICC Application Programming Interface for Java Card[™] for Contactless Applications; Test Environment and Annexes
 - Scope: creation of a test specification covering Contactless UICC API conformance requirements specified in TSI TS 102 705

4th Form Factor (Requirements and Technical Solution)

- Scope: Collection of use cases and requirements for a UICC form factor smaller by 25% to 40% than the one known as Mini-UICC or 3FF. While smaller, this form factor would retain the existing UICC functionalities
- Scope: Development of the technical specifications for a fourth UICC form factor in accordance with the technical requirements and selection criteria

P2P mode for contactless communications

• Definition of the support of P2P mode in contactless specifications according to the agreed requirements in TS 102 412.

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